



## FEATURES

- Fast Switching
- Low ON Resistance
- Low Gate Charge
- 100% Single Pulse avalanche energy Test

## APPLICATIONS

- Load Switch
- PWM Application
- Power management

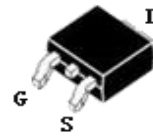
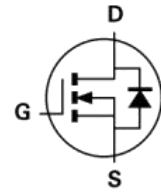
## MECHANICAL DATA

- Case: Molded plastic
- Mounting Position: Any
- Molded Plastic: UL Flammability Classification Rating 94V-0
- Lead free in compliance with EU RoHS 2011/65/EU directive
- Solder bath temperature 275°C maximum, 10s per JESD 22-B106

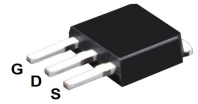
## MAIN CHARACTERISTICS

ID	50A
VDSS	60V
RDSON-typ (@VGS=10V)	12mΩ

## PACKAGE



TO-252



TO-251

## Product specification classification

Part Number	Package	Mode Name	Pack
LX50N06AD	TO-252	LX50N06AD	Tape
LX50N06AU	TO-251	LX50N06AU	Tape



**Maximum Ratings at  $T_c=25^\circ\text{C}$  unless otherwise specified**

Characteristics	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	60	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continue Drain Current	$I_D$	50	A
Pulsed Drain Current (Note1)	$I_{DM}$	200	A
Power Dissipation	$P_D$	75	W
Single Pulse Avalanche Energy (Note5)	$E_{AS}$	80	mJ
Operating Temperature Range	$T_J$	150	$^\circ\text{C}$
Storage Temperature Range	$T_{STG}$	-55 to +150	$^\circ\text{C}$
Thermal Resistance, Junction to Case(Note 2)	$R_{\theta JC}$	2	$^\circ\text{C/W}$
Thermal Resistance, Junction to AmbientZ	$R_{\theta JA}$	62	$^\circ\text{C/W}$

Note1:Pulse test: 300  $\mu\text{s}$  pulse width, 2 % duty cycle

**Electrical Characteristics at  $T_c=25^\circ\text{C}$  unless otherwise specified**

Characteristics	Test Condition	Symbol	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_D = 250\ \mu\text{A}$	$BV_{DSS}$	60	-	-	V
Drain-Source Leakage Current	$V_{DS} = 60\text{V}, V_{GS} = 0\text{ V}$	$I_{DSS}$	-	-	1	$\mu\text{A}$
Gate Leakage Current	$V_{GS} = \pm 20\text{ V}, V_{DS} = 0\text{ V}$	$I_{GSS}$	-	-	$\pm 100$	nA
Gate-Source Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\ \mu\text{A}$	$V_{GS(th)}$	1	-	2.5	V
Drain-Source On-State Resistance (Note 3)	$V_{GS} = 10\text{ V}, I_D = 30\text{A}$	$R_{DS(on)}$	-	12	17	$\text{m}\Omega$
	$V_{GS} = 4.5\text{ V}, I_D = 20\text{A}$	$R_{DS(on)}$	-	16	25	$\text{m}\Omega$
Input Capacitance	$V_{GS} = 0\text{ V}, V_{DS} = 25\text{ V}, f = 1\text{ MHz}$	$C_{iss}$	-	2030	-	pF
Output Capacitance		$C_{oss}$	-	130	-	pF
Reverse Transfer Capacitance		$C_{rss}$	-	115	-	pF
Turn-on Delay Time		$t_{d(ON)}$	-	11	-	ns
Rise Time	$V_{DD}=30\text{V}, V_{GS}=10\text{V}, RG=1.8\Omega, I_D=30\text{A}$	$t_r$	-	79	-	ns
Turn-Off Delay Time		$t_{d(OFF)}$	-	33	-	ns
Fall Time		$t_f$	-	105	-	ns
Total Gate Charge	$V_{DS}=30\text{V}, V_{GS}=10\text{V}, I_D=30\text{A}$	$Q_G$	-	45	-	nC
Gate to Source Charge		$Q_{GS}$	-	8	-	nC
Gate to Drain Charge		$Q_{GD}$	-	11	-	nC

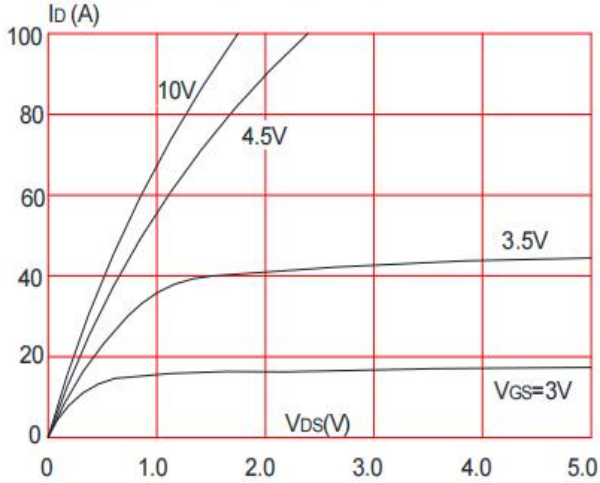
**Source-Drain Diode Characteristics at  $T_a=25^\circ\text{C}$  unless otherwise specified**

Characteristics	Test Condition	Symbol	Min.	Typ.	Max.	Unit
Maximun Body-Diode Continuous Current (Note 2)		$I_S$	-	-	50	A
Maximun Body-Diode Pulsed Current		$I_{SM}$	-	-	200	A
Drain-Source Diode Forward Voltage (Note 3)	$I_{SD} = 30\text{A}$	$V_{SD}$	-	-	1.2	V
Reverse Recovery Time	$I_S = I_F, I_{SD}=30\text{A}, V_{GS} = 0\text{ V},$	$t_{rr}$	-	14	-	ns
Reverse Recovery Charge	$dI / dt = 100\text{ A}/\mu\text{s}$ (Note3)	$Q_{rr}$	-	10	-	$\mu\text{C}$

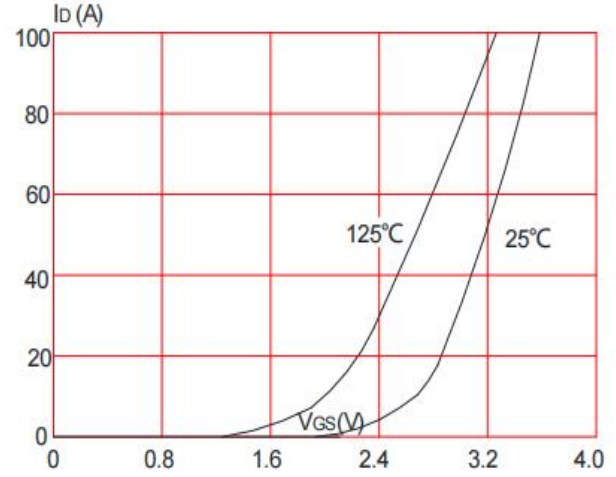
Note2:Pulse test: 300  $\mu\text{s}$  pulse width, 2 % duty cycle

**RATINGS AND CHARACTERISTIC CURVES**

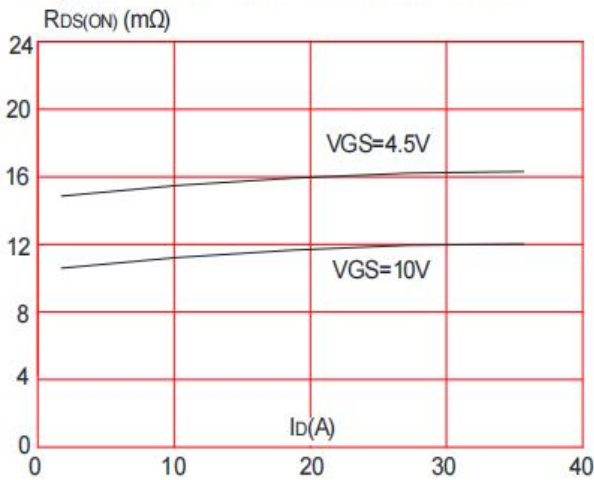
**Figure 1: Output Characteristics**



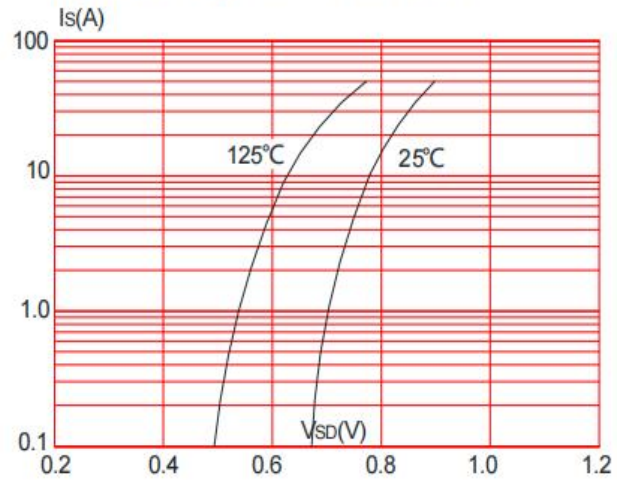
**Figure 2: Typical Transfer Characteristics**



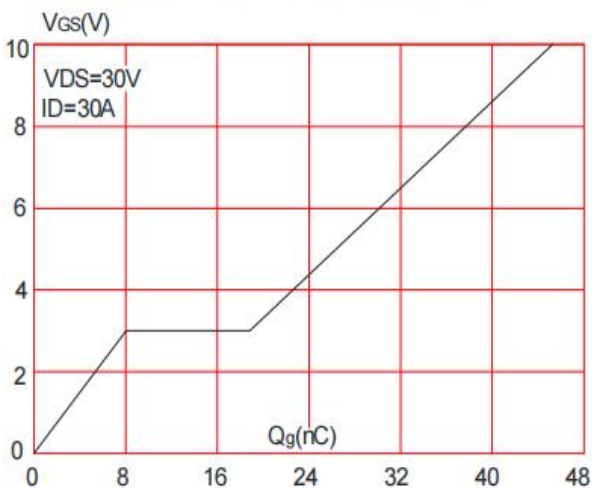
**Figure 3: On-resistance vs. Drain Current**



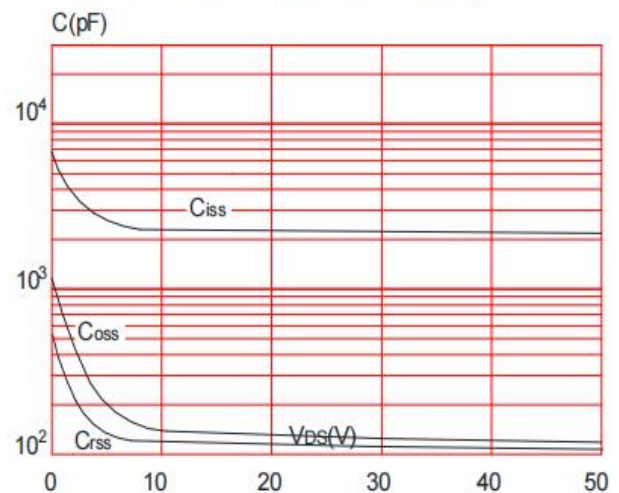
**Figure 4: Body Diode Characteristics**



**Figure 5: Gate Charge Characteristics**

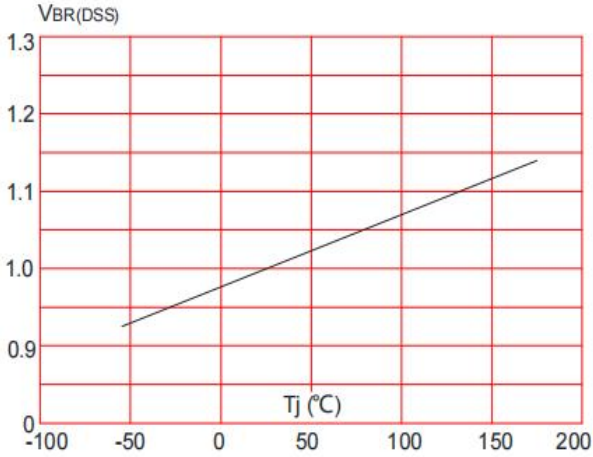


**Figure 6: Capacitance Characteristics**

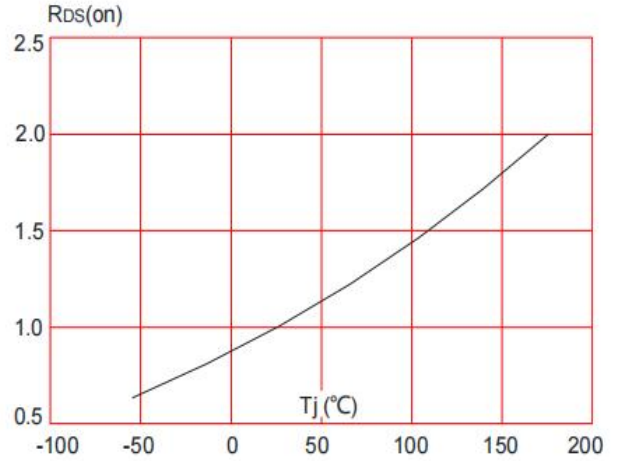


**RATINGS AND CHARACTERISTIC CURVES**

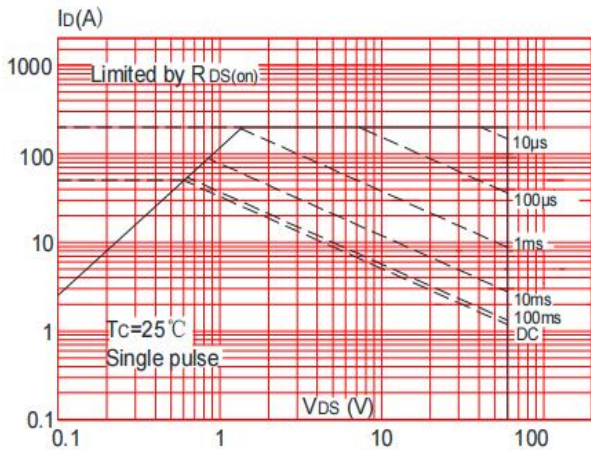
**Figure 7: Normalized Breakdown Voltage vs. Junction Temperature**



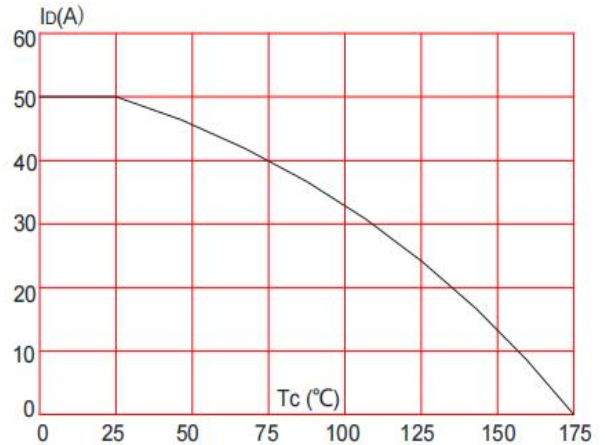
**Figure 8: Normalized on Resistance vs. Junction Temperature**



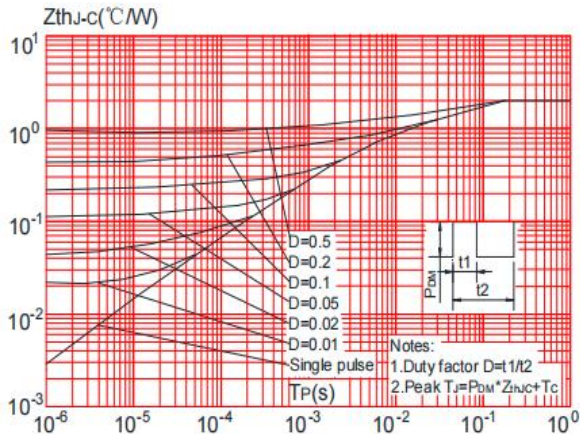
**Figure 9: Maximum Safe Operating Area**



**Figure 10: Maximum Continuous Drain Current vs. Case Temperature**

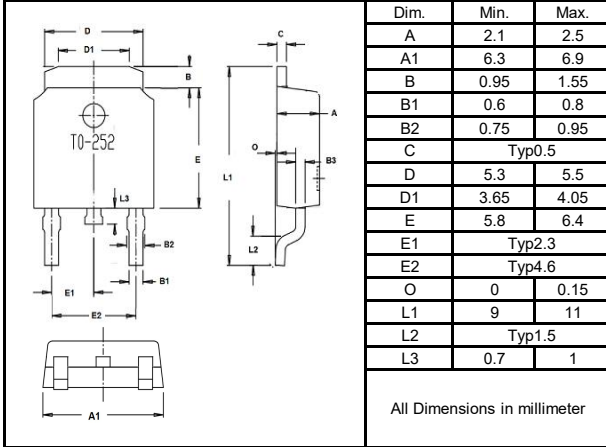


**Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Case**



Package Outline Dimensions millimeters

T0-252



T0-251

